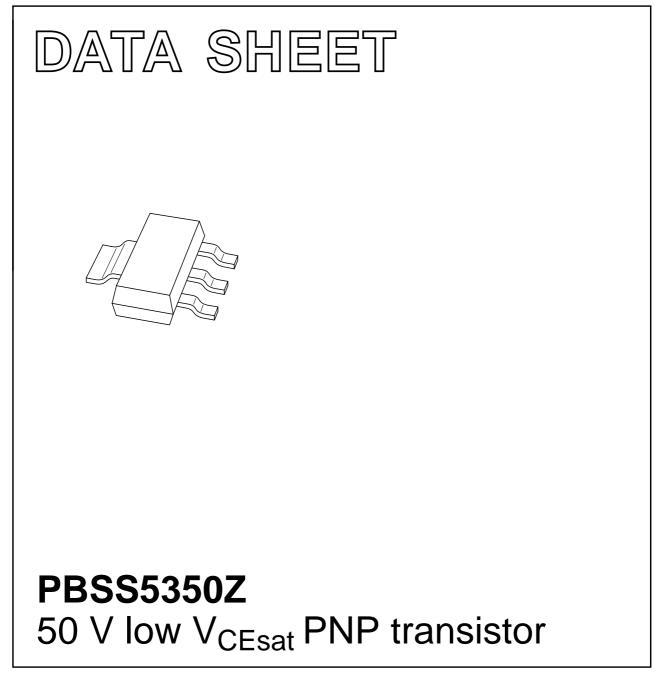
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2003 Jan 20 2003 May 13



FEATURES

- Low collector-emitter saturation voltage
- High collector current capability: I_{C} and I_{CM}
- High collector current gain (h_{FE}) at high I_C
- Higher efficiency leading to less heat generation
- Reduced PCB area requirements compared to DPAK.

APPLICATIONS

- Power management
 - DC/DC converters
 - Supply line switching
 - Battery charger
 - Linear voltage regulation (LDO).
- Peripheral drivers
 - Driver in low supply voltage applications, e.g. lamps, LEDs
 - Inductive load driver, e.g. relays, buzzers, motors.

DESCRIPTION

PNP low V_{CEsat} transistor in a SOT223 plastic package. NPN complement: PBSS4350Z.

MARKING

TYPE NUMBER	MARKING CODE			
PBSS5350Z	PB5350			

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-50	V
I _C	collector current (DC)	-3	A
I _{CM}	peak collector current	-5	А
R _{CEsat}	equivalent on-resistance	<150	mΩ

PINNING

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	
4	collector	

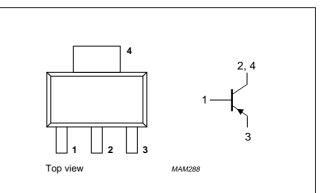


Fig.1 Simplified outline (SOT223) and symbol.

PBSS5350Z

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-60	V
V _{CEO}	collector-emitter voltage	open base	-	-50	V
V _{EBO}	emitter-base voltage	open collector	-	-6	V
I _C	collector current (DC)		_	-3	A
I _{CM}	peak collector current		-	-5	A
I _{BM}	peak base current		_	-1	A
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; notes 1 and 3	_	1.35	W
		$T_{amb} \le 25 \ ^{\circ}C$; notes 2 and 3	-	2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 3. For other mounting conditions see "Thermal considerations for SOT223 in the General Part of associated Handbook".

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air; notes 1 and 3	92	K/W
		in free air; notes 2 and 3	62.5	K/W

Notes

- 1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 3. For other mounting conditions see "Thermal considerations for SOT223 in the General Part of associated Handbook".

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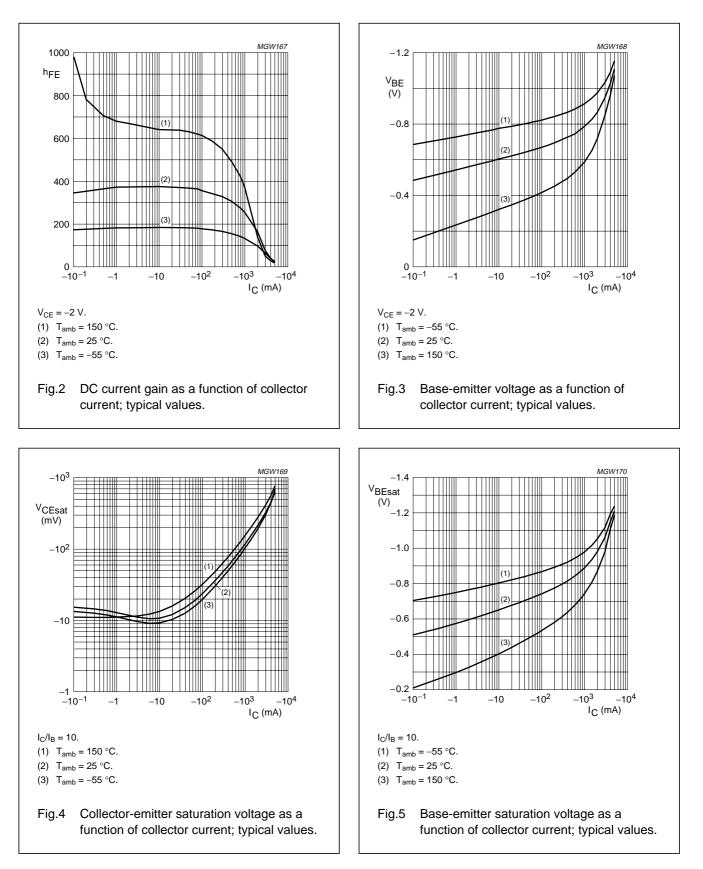
CHARACTERISTICS

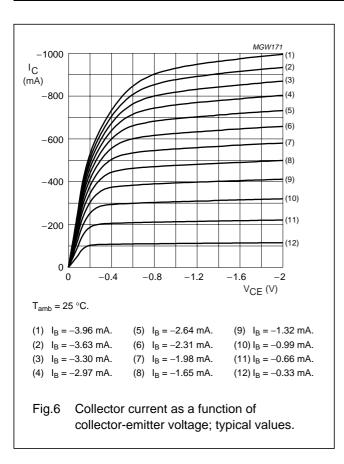
 T_{amb} = 25 °C unless otherwise specified.

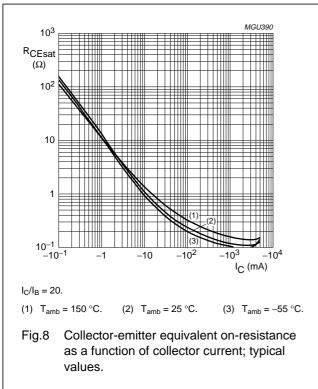
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	-	-	-100	nA
		$V_{CB} = -50 \text{ V}; I_E = 0; T_j = 150 \text{ °C}$	-	-	-50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0$	-	-	-100	nA
h _{FE}	DC current gain	$V_{CE} = -2 V;$				
		I _C = -500 mA	200	-	-	
		I _C = -1 A; note 1	200	-	-	
		I _C = -2 A; note 1	100	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{\rm C} = -500 \text{ mA}; I_{\rm B} = -50 \text{ mA}$	_	-	-100	mV
		$I_{\rm C} = -1$ A; $I_{\rm B} = -50$ mA	-	-	-180	mV
		$I_{\rm C} = -2$ A; $I_{\rm B} = -200$ mA; note 1	_	-	-300	mV
R _{CEsat}	equivalent on-resistance	$I_{\rm C} = -2$ A; $I_{\rm B} = -200$ mA; note 1	_	120	<150	mΩ
V _{BEsat}	base-emitter saturation voltage	$I_{\rm C} = -2$ A; $I_{\rm B} = -200$ mA; note 1	-	-	-1.2	V
V _{BEon}	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; I_{C} = -1 \text{ A}; \text{ note } 1$	_	-	-1.1	V
f _T	transition frequency	$I_{C} = -100 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	100	-	-	MHz
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	-	-	40	pF

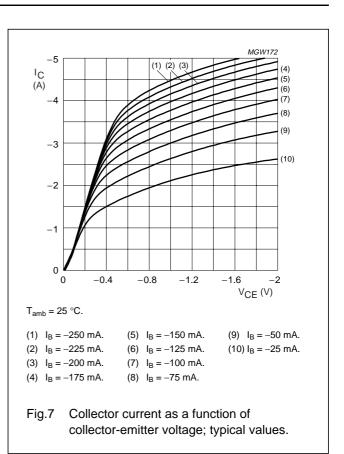
Note

1. Pulse test: $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$

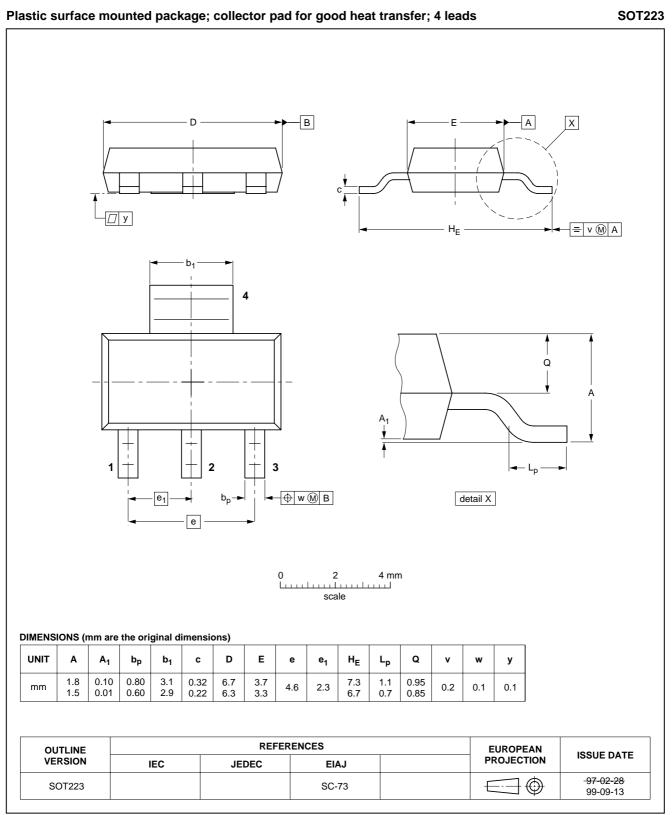








PACKAGE OUTLINE



PBSS5350Z

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
1	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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